

ENVIRONMENTAL AND ENDURANCE TESTING – TEST METHODS FOR SURFACE-MOUNT BOARDS OF
AREA ARRAY TYPE PACKAGES FBGA, BGA, FLGA, LGA, SON AND QFN

CORRIGENDUM 1

Page 5

2 Normative references

Delete:

IEC 61190-1-1, *Attachment materials for electronic assemblies – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-2, *Attachment materials for electronic assemblies – Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly*

IEC 61190-1-3, *Attachment materials for electronic assemblies – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

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A.2.4.4 Post-treatment (flux removal)

First sentence

Instead of:

“(propanol)”

read:

“(isopropanol)”.

Page 17

A.3.4.1 Soldering process, a) Pre-treatment

Instead of:

“as specified in Figure 3”

read:

“as specified in Figure 2”.